



J. Lienig, S. Rothe, M. Thiele

Fundamentals of Electromigration-Aware Integrated Circuit Design

- Enables readers to understand and meet challenges of electromigration, including its effects on circuit reliability
- Accessible to readers of varying backgrounds, combining practical application with theoretical underpinnings
- Multiple examples and hands-on instructions for the practical application of counter measures

Second Edition 2025.
XV, 167 p. 100 illus., 95 illus. in color.

Printed version

Hardcover
€ (D) 139,09 | € (A) 142,99 |
CHF 153.50
ISBN 978-3-031-80022-1

eBook

€ 111,27 | CHF 123.00
ISBN 978-3-031-80023-8

[https://link.springer.com/
book/10.1007/978-3-031-800
23-8](https://link.springer.com/book/10.1007/978-3-031-80023-8)

The book provides a comprehensive overview of electromigration and its effects on the reliability of electronic circuits. This second edition has been updated to introduce recent advancements in the understanding of the physical process of electromigration, which gives the reader the knowledge for adopting appropriate counter measures. A comprehensive set of options is presented for modifying the present IC design methodology to prevent electromigration. Finally, the authors show how specific effects can be exploited in present and future technologies to reduce electromigration's negative impact on circuit reliability.

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